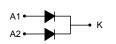
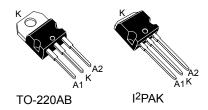
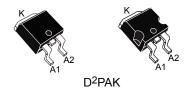




# 100 V power Schottky rectifier







#### **Features**

- · Negligible switching losses
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- · Low thermal resistance
- · Avalanche specification
- ECOPACK®2 compliant

### **Applications**

- · Switching diode
- SMPS
- DC/DC converter
- · LED lighting
- · Desktop power supply

#### **Description**

This dual center tab Schottky rectifier is suited for switch mode power supply and high frequency DC to DC converters.

Packaged in D $^2$ PAK, I $^2$ PAK and TO-220AB, the STPS41H100C is optimized for use in high frequency inverters.

Product status link				
STPS41H100C				
Product summary				
Symbol Value				
I <sub>F(AV)</sub>	2 x 20 A			
V <sub>RRM</sub>	100 V			
Тј	175 °C			
V <sub>F</sub> (typ.)	0.62 V			



#### 1 Characteristics

Table 1. Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified)

Symbol	Symbol Parameter				Unit
$V_{RRM}$	Repetitive peak reverse voltage			100	V
I <sub>F(RMS)</sub>	Forward rms current			30	Α
I	$I_{F(AV)}$ Average forward current, $\delta$ = 0.5 square wave $T_c$	T <sub>c</sub> = 150 °C	Per diode	20	A
'F(AV)		1 <sub>c</sub> = 150 C	Per device	40	
I <sub>FSM</sub>	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$		220	Α	
P <sub>ARM</sub>	Repetitive peak avalanche power $t_p$ = 10 $\mu$ s, $T_j$ = 125 $^{\circ}$ C		1300	W	
T <sub>stg</sub>	Storage temperature range			-65 to +175	°C
Tj	T <sub>j</sub> Maximum operating junction temperature range <sup>(1)</sup>			175	°C

<sup>1.</sup>  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	Parameter		Max. value	Unit
D., ., .	Junction to case	Per diode	1.5	°C/W
$R_{th(j-c)}$	Junction to case	Total	0.8	
R <sub>th(c)</sub>	Coupling		0.1	

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_i(diode 1) = P(diode 1) \times R_{th(i-c)}(per diode) + P(diode 2) \times R_{th(c)}$ 

For more information, please refer to the following application note:

• AN5088 : Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
ı (1)	I <sub>R</sub> <sup>(1)</sup> Reverse leakage current	T <sub>j</sub> = 25 °C	\/- <b>-</b> \/	-		10	μA
'R''		T <sub>j</sub> = 125 °C	$V_R = V_{RRM}$	-	3	10	mA
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 20 A	-		0.80	
V <sub>F</sub> <sup>(2)</sup>	Farward voltage drap	T <sub>j</sub> = 125 °C		-	0.62	0.67	V
VF <sup>(-)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 40 A	-		0.90	V
		T <sub>j</sub> = 125 °C	1F - 40 A	-	0.70	0.76	

- 1. Pulse test:  $t_p = 5$  ms,  $\delta < 2\%$
- 2. Pulse test:  $t_p = 380 \ \mu s, \ \delta < 2\%$

To evaluate the conduction losses, use the following equation:  $P = 0.58 \times I_{F(AV)} + 0.0045 \times I_{F}^{2}(RMS)$ 

For more information, please refer to the following application notes related to the power losses:

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

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#### 1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current (per diode)

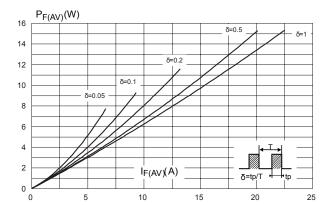


Figure 2. Average forward current versus ambient temperature ( $\delta$  = 0.5, per diode)

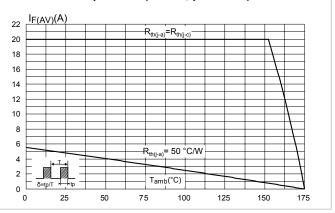


Figure 3. Normalized avalanche power derating versus pulse duration (T<sub>i</sub> = 125 °C)

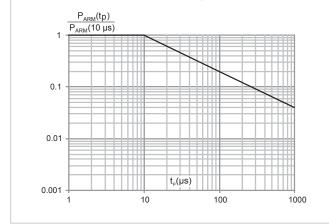
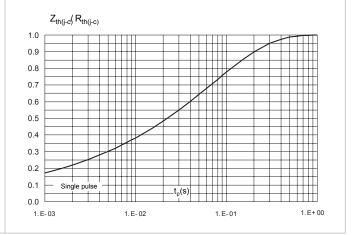


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration



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Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode)

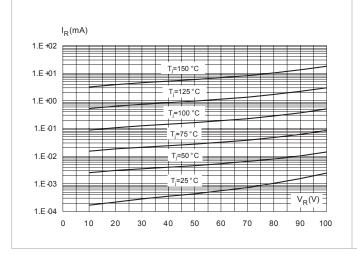


Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)

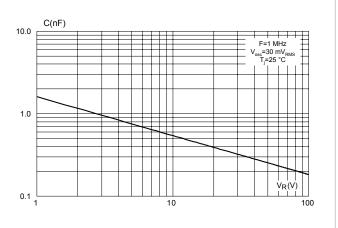


Figure 7. Forward voltage drop versus forward current (per diode)

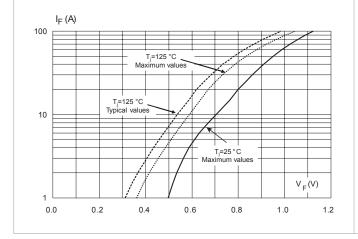
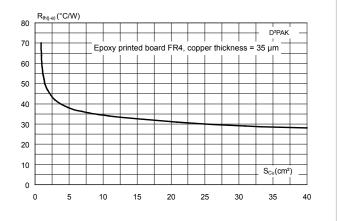


Figure 8. Thermal resistance junction to ambient versus copper surface under tab



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# 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

## 2.1 TO-220AB package information

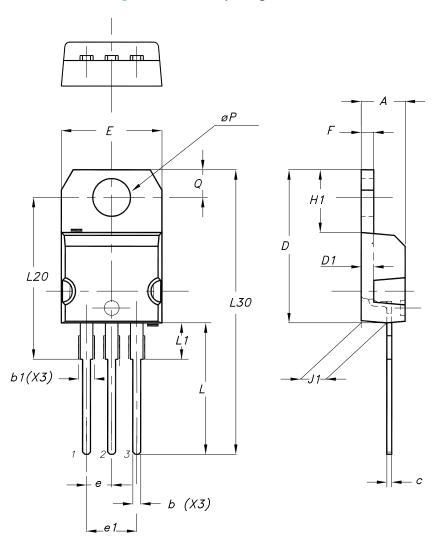
• Epoxy meets UL 94,V0

Cooling method: by conduction (C)

Recommended torque value: 0.55 N·m

Maximum torque value: 0.70 N·m

Figure 9. TO-220AB package outline



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Table 4. TO-220AB package mechanical data

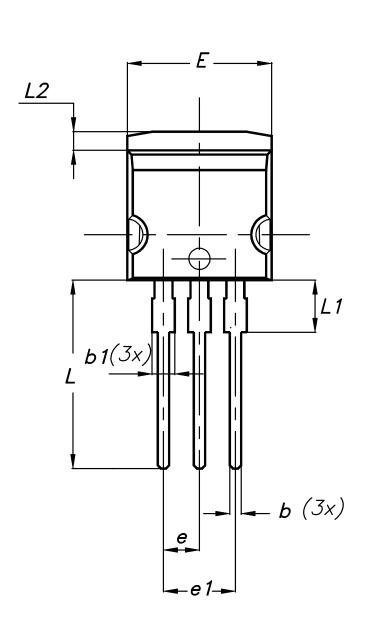
	Dimensions			
Ref.	Millimeters		Inches (for re	ference only)
	Min.	Max.	Min.	Max.
Α	4.40	4.60	0.173	0.181
b	0.61	0.88	0.240	0.035
b1	1.14	1.55	0.045	0.061
С	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
D1	1.27 typ.		0.050	typ.
E	10.00	10.40	0.394	0.409
е	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.244	0.260
J1	2.40	2.72	0.094	0.107
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.646 typ.	
L30	28.9	90 typ.	1.138	typ.
θР	3.75	3.85	0.148	0.152
Q	2.65	2.95	0.104	0.116

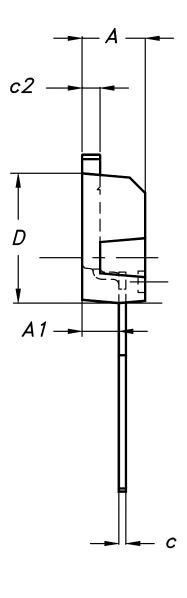


# 2.2 I<sup>2</sup>PAK package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)

Figure 10. I<sup>2</sup>PAK package outline





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Table 5. I<sup>2</sup>PAK package mechanical data

	Dimensions				
Ref.	Millimeters		Inches (for re	ference only)	
	Min.	Max.	Min.	Max.	
Α	4.40	4.60	0.173	0.181	
A1	2.40	2.72	0.094	0.107	
b	0.61	0.88	0.024	0.035	
b1	1.14	1.70	0.044	0.067	
С	0.49	0.70	0.019	0.028	
c2	1.23	1.32	0.048	0.052	
D	8.95	9.35	0.352	0.368	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
E	10.00	10.40	0.394	0.409	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L2	1.27	1.40	0.050	0.055	

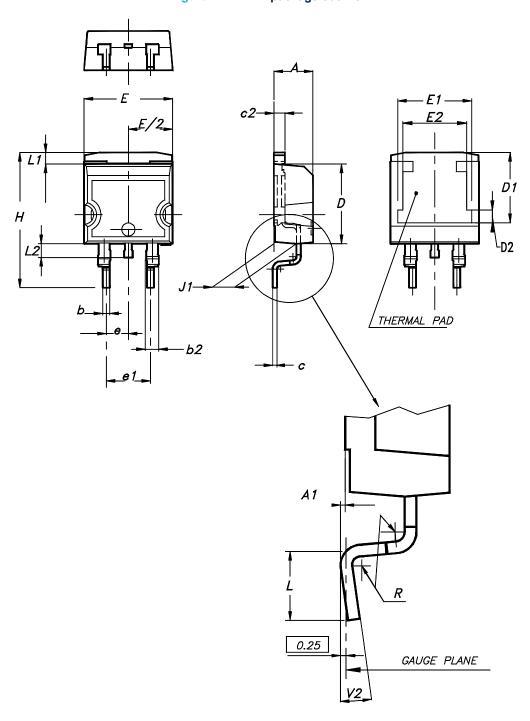
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## 2.3 D<sup>2</sup>PAK package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

Figure 11. D<sup>2</sup>PAK package outline



Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

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Table 6. D<sup>2</sup>PAK package mechanical data

	Dimensions			
Ref.	Millimeters		Inches (for re	ference only)
	Min.	Max.	Min.	Max.
А	4.36	4.60	0.172	0.181
A1	0.00	0.25	0.000	0.010
b	0.70	0.93	0.028	0.037
b2	1.14	1.70	0.045	0.067
С	0.38	0.69	0.015	0.027
c2	1.19	1.36	0.047	0.053
D	8.60	9.35	0.339	0.368
D1	6.90	8.00	0.272	0.311
D2	1.10	1.50	0.043	0.060
E	10.00	10.55	0.394	0.415
E1	8.10	8.90	0.319	0.346
E2	6.85	7.25	0.266	0.282
е	2.54	typ.	0.100	
e1	4.88	5.28	0.190	0.205
Н	15.00	15.85	0.591	0.624
J1	2.49	2.90	0.097	0.112
L	1.90	2.79	0.075	0.110
L1	1.27	1.65	0.049	0.065
L2	1.30	1.78	0.050	0.070
R	0.4	typ.	0.0	15
V2	0°	8°	0°	8°



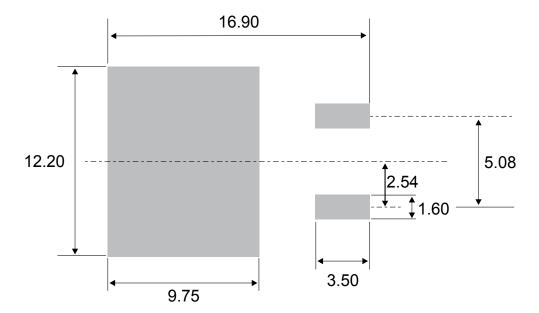


Figure 12. D<sup>2</sup>PAK recommended footprint (dimensions in mm)

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# **3** Ordering information

**Table 7. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS41H100CT	STPS41H100CT	TO-220AB	1.95 g	50	Tube
STPS41H100CG	STPS41H100CG	D <sup>2</sup> PAK	1.38 g	50	Tube
STPS41H100CG-TR	STPS41H100CG	D <sup>2</sup> PAK	1.38 g	10000	Tape and reel
STPS41H100CR	STPS41H100CR	I <sup>2</sup> PAK	1.50 g	30	Tube

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# **Revision history**

**Table 8. Document revision history** 

Date	Version	Changes
Jul-2003	3A	Previous release.
15-Jul-2011	4	Updated Table 5.
11-Apr-2012	5	Removed order codes STPS41H100CR-H and STPS41H100CT-H. Replaced paragraph under Table 5.
27-Jun-2018	6	Updated Table 1. Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified). Updated Section 1.1 Characteristics (curves).



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